

Subst. Form PTO-1449 APPLICANTS' INFORMATION DISCLOSURE STATEMENT	Atty. Docket No.: FLCZ 2 00288-2-1	Serial No.: Unknown
	Applicants: DUVALL, et al.	
	Filing Date: Herewith	Group: Unknown

U.S. PATENT DOCUMENTS							
Initial*		Document No.	Date	Name	Class	Subcl.	Filing Date
AA		6,054,198	April 25, 2000	Bunyan, et al.			
AB		5,904,796	May 18, 1999	Freuler, et al.			
AC		5,783,862	July 21, 1998	Deeney			
AD		5,770,318	June 23, 1998	Friedman			
AE		5,302,344	April 12, 1994	Perlman			
AF		5,290,624	March 1, 1994	Bujard			
AG		4,915,167	April 10, 1990	Altoz			
AH		4,879,632	November 7, 1989	Yamamoto, et al.			
AI		4,729,060	March 1, 1988	Yamamoto, et al.			
AJ		4,722,960	February 2, 1988	Dunn, et al.			
AK		4,685,987	August 11, 1987	Fick			
AL		4,487,856	December 11, 1984	Anderson, et al.			
AM		4,299,715	November 1, 1981	Whitfield, et al.			
FOREIGN PATENT DOCUMENTS							
		Document No.	Date	Country	Class	Subcl.	Translation?
AN		1-248551 (A)	October 4, 1989	Japan			Yes
OTHER ART							
AO		"Packaging Ideas", Electronic Packaging & Production, September 1, 1995, page 32.					
AP		R.C. Miller, "Structure for Achieving Thermal Enhancement in a Semiconductor Package," IBM Technical Disclosure Bulletin, Vol. 23, No. 6, November 1980, page 2308.					
AQ		"Thermal Sponge," IBM Technical Disclosure Bulletin, Vol. 29, No. 11, April 1987, pages 4950-4951.					
AR		C. Biber, "Choosing a Heat Sink: Some Tips and Recommendations," EDN, October 12, 1995, pages 125-133.					
AS		J.G. Ameen, et al. "Dealing with the Heat," Circuits & Devices, July 1998, pages 38-40.					
AT		R.J. Dombrowskas, et al., "Conduction Cooled Chip Module," IBM Technical Disclosure Bulletin, Vol. 14, No. 9, February 1972, page 2689.					
Examiner: <i>W.C. [Signature]</i>					Date Considered: 7/1/94		
<p>* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if in conformance and not considered. Include copy of this form with next communication to applicant.</p>							

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U.S. PATENT DOCUMENTS							
Initial*		Document No.	Date	Name	Class	Subcl.	Filing Date
	BA	5,737,187	April 7, 1998	Nguyen, et al.			
	BB	5,901,040	May 4, 1999	Cromwell, et al.			
	BC	5,930,115	July 27, 1999	Tracy, et al.			
	BD	5,679,457	October 21, 1997	Bergerson			
	BE						
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	BK						
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FOREIGN PATENT DOCUMENTS							
		Document No.	Date	Country	Class	Subcl.	Translation?
	BN	EP 0 813 244 A2	June 12, 1997	Europe			
	BO	WO 97/41599	November 6, 1997	PCT			
	BP	WO 99/19909	April 22, 1999	PCT			
	BQ	EP 1 067 164 A1	July 7, 2000	Europe			

OTHER ART		
	BO	
	BP	

Examiner:	Date Considered: 7/1/04
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